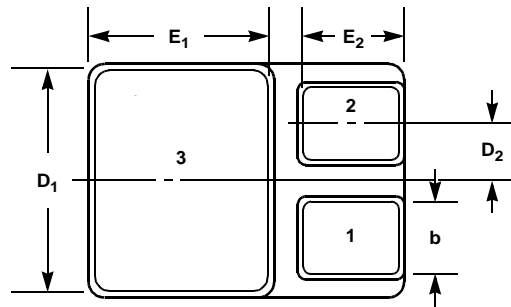
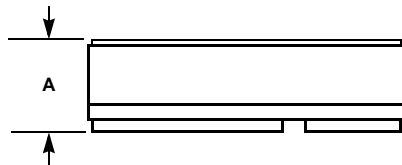
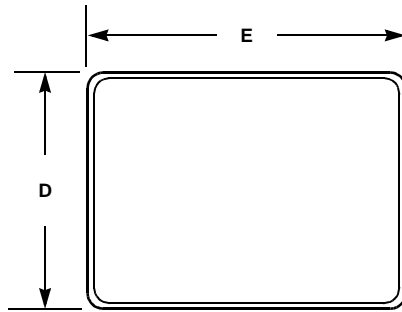


SMD.5

3 PAD CERAMIC LEADLESS CHIP CARRIER



1 - GATE
2 - SOURCE
3 - DRAIN

| SYMBOL | INCHES | | MILLIMETERS | | NOTES |
|----------------|--------|-------|-------------|------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.11 | 0.124 | 2.84 | 3.15 | 3 |
| b | 0.09 | 0.100 | 2.28 | 2.54 | - |
| D | 0.29 | 0.301 | 7.39 | 7.64 | - |
| D ₁ | 0.28 | 0.291 | 7.13 | 7.39 | - |
| D ₂ | 0.07 | 0.080 | 1.78 | 2.03 | - |
| E | 0.39 | 0.405 | 10.0 | 10.2 | - |
| E ₁ | 0.22 | 0.230 | 5.58 | 5.84 | - |
| E ₂ | 0.11 | 0.125 | 2.92 | 3.17 | - |

NOTES:

1. No current JEDEC outline for this package.
2. Controlling dimension: Inch.
3. Measurement prior to pre-solder coating the mounting pads.
4. Revision 4 dated 5-00.